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[Digital Cross Connect System Pdf](#)

DS3171/DS3172/DS3173/DS3174 Single/Dual/Triple/Quad DS3/E3 Single-Chip Transceivers

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GENERAL DESCRIPTION

The DS3171, DS3172, DS3173, and DS3174 (DS317x) combine a DS3/E3 framer(s) and LIU(s) to interface to as many as four DS3/E3 physical copper lines.

APPLICATIONS

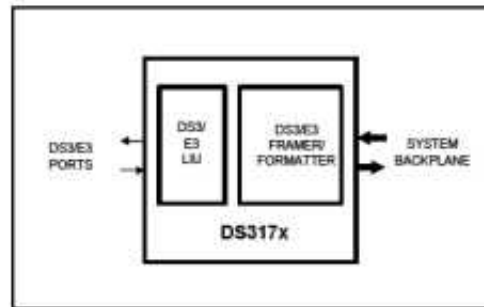
Access Concentrators	Multiservice Access Platform (MSAP)
SONET/SDH ADM and Muxes	Multiservice Protocol Platform (MSPP)
PBXs	PDH Multiplexer/Demultiplexer
Digital Cross Connect Test Equipment	Integrated Access Device (IAD)
Routers and Switches	

ORDERING INFORMATION

PART	TEMP RANGE	PIN-PACKAGE
DS3171*	0°C to +70°C	400 TE-CSBGA (27mm x 27mm, 1.27mm pitch)
DS3171N*	-40°C to +85°C	400 TE-CSBGA (27mm x 27mm, 1.27mm pitch)
DS3172*	0°C to +70°C	400 TE-CSBGA (27mm x 27mm, 1.27mm pitch)
DS3172N*	-40°C to +85°C	400 TE-CSBGA (27mm x 27mm, 1.27mm pitch)
DS3173*	0°C to +70°C	400 TE-CSBGA (27mm x 27mm, 1.27mm pitch)
DS3173N*	-40°C to +85°C	400 TE-CSBGA (27mm x 27mm, 1.27mm pitch)
DS3174	0°C to +70°C	400 TE-CSBGA (27mm x 27mm, 1.27mm pitch)
DS3174N	-40°C to +85°C	400 TE-CSBGA (27mm x 27mm, 1.27mm pitch)

*Future product—contact factory for availability.

FUNCTIONAL DIAGRAM



FEATURES

- Single (DS3171), Dual (DS3172), Triple (DS3173), or Quad (DS3174) Single-Chip Transceiver for E3 and DS3
- All Four Devices are Pin Compatible for ease of Port Density Migration in the Same Printed Circuit Board Platform
- Each Port Independently Configurable
- Performs Receive Clock/Data Recovery and Transmit Waveshaping for DS3 and E3
- Jitter Attenuator can be Placed Either in the Receive or Transmit Paths
- Interfaces to 75Ω Coaxial Cable at Lengths Up to 380 meters, or 1246 feet (DS3) or 440 meters, or 1443 feet (E3)
- Uses 1:2 Transformers on Both Tx and Rx
- On-Chip DS3 (M23 or C-Bit) and E3 (G.751 or G.832) Framer(s)
- Ports Independently Configurable for DS3, E3
- Built-In HDLC Controllers with 256-Byte FIFOs for the Insertion/Extraction of DS3 PMDL, G.751 Sn Bit, and G.832 NR/GC Bytes
- On-Chip BERTs for PRBS and Repetitive Pattern Generation, Detection, and Analysis
- Large Performance-Monitoring Counters for Accumulation Intervals of at Least 1 Second
- Flexible Overhead Insertion/Extraction Ports for DS3, E3 Framers

Note: Some revisions of this device may incorporate deviations from published specifications known as errata. Multiple revisions of any device may be simultaneously available through various sales channels. For information about device errata, click here: www.maxim-ic.com/errata

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Digital Cross-Connect (DXC) The cross-connecting of circuits is done when circuits are provisioned, but, typically, cross-connects are also used to implement various schemes for protection switching and network restoration.. A distributed digital cross-connect system (10) is provided The system includes two or more network interface islands (12) that connect to the telecommunications network.

1. [digital cross connect system](#)
2. [digital cross connect system architecture](#)
3. [digital cross-connect system unit](#)

The system (10) also includes one or more distributed services nodes (18) New Generation Digital Cross-connect System [PAGE 1 OF 3] New Generation DCS The Digital Cross-connect System (DCS or DXC) performs a critical role in a network operator's transport or backhaul network.. In the SDH market, the abbreviation “DXC” is used for digital cross-connects, whereas they are referred to as “DCSs” in the SONET world.

digital cross connect system

digital cross connect system, digital cross connect system ppt, digital cross connect system architecture, digital cross connect system pdf, digital cross-connect system unit, how does a digital cross-connect system work, what are the types of digital cross-connect system, wideband digital cross-connect system, digital access and cross-connect system (dacs), digital access cross connect system, digital cross connect equipment [Diamond Nail File Boots - Free Software and Shareware](#)

Designed to optimize network efficiency, these platforms switch and groom bandwidth at multiple levels of granularity for hand-off to the IOF. [Tools For Business Growth - Download Free Apps](#)

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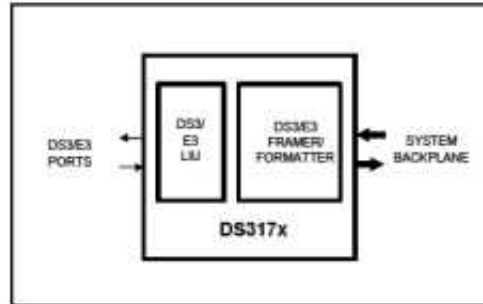
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DS3173N*	-40°C to +85°C	400 TE-CSBGA (27mm x 27mm, 1.27mm pitch)
DS3174	0°C to +70°C	400 TE-CSBGA (27mm x 27mm, 1.27mm pitch)
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